

(12) 按照专利合作条约所公布的国际申请

(19) 世界知识产权组织
国际局



(10) 国际公布号
WO 2024/244924 A1

(43) 国际公布日
2024 年 12 月 5 日 (05.12.2024)

(51) 国际专利分类号:
C25D 21/04 (2006.01) **C25D 7/12** (2006.01)
C25D 17/00 (2006.01) **C25D 3/48** (2006.01)

(21) 国际申请号: PCT/CN2024/091691

(22) 国际申请日: 2024 年 5 月 8 日 (08.05.2024)

(25) 申请语言: 中文

(26) 公布语言: 中文

(30) 优先权:
202310609132.3 2023 年 5 月 26 日 (26.05.2023) CN

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(54) Title: ELECTROPLATING APPARATUS AND ELECTROPLATING SYSTEM

(54) 发明名称: 电镀装置及电镀系统

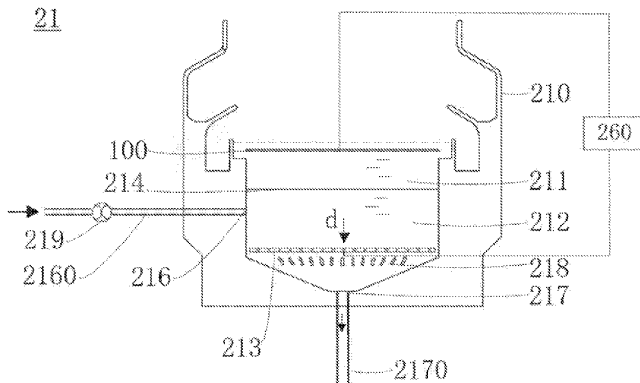


图 3

(57) Abstract: An electroplating apparatus and an electroplating system. The electroplating apparatus (21) comprises: an electroplating bath (210) used for accommodating an electroplating solution and a substrate (100); a non-soluble anode (213) provided inside the electroplating bath (210) and located below the substrate (100); an anode solution inlet (216) used for supplying the electroplating solution into the electroplating bath; and an anode solution outlet (217) used for discharging the electroplating solution from the electroplating bath. The anode solution inlet (216) is higher than the non-soluble anode (213) and the anode solution outlet (217), such that the electroplating solution flows in a first direction away from the substrate between the anode solution inlet and the anode solution outlet during electroplating; the flow velocity of the electroplating solution in the electroplating bath is set such that the electroplating solution applies an acting force toward the first direction to bubbles generated on the surface of the non-soluble anode; and the acting

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MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW。

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本国际公布:

— 包括国际检索报告(条约第21条(3))。

force is greater than the buoyancy of the bubbles, such that the bubbles are away from the substrate, thereby overcoming the problem of the quality of the substrate being affected due to the non-soluble anode generating more bubbles during electroplating of the substrate.

(57) 摘要: 一种电镀装置及电镀系统, 该电镀装置(21)包括: 镀槽(210), 用于容纳电镀液和基板(100); 非可溶性阳极(213), 配置于镀槽(210)内部且位于基板(100)下方; 阳极液入口(216), 用于向镀槽内供应电镀液; 阳极液出口(217), 用于从镀槽排放电镀液。其中, 阳极液入口(216)高于非可溶性阳极(213)和阳极液出口(217), 以使在进行电镀作业时电镀液在阳极液入口和阳极液出口之间形成沿远离基板的第一方向流动, 且电镀槽内的电镀液流速被配置为, 使电镀液对非可溶性阳极表面产生的气泡施加朝向所述第一方向的作用力, 且作用力大于气泡的浮力, 以使气泡远离基板, 进而克服不溶性阳极在基板电镀期间会产生较多气泡影响基板品质的问题。